

# PRODUCT / PROCESS CHANGE NOTIFICATION

## 1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	AMG/18/10676	
1.3 Title of PCN	Additional wafer fab in ST Ang Mo Kio (Singapore) for PMOS SUPERMESH products with new BOM on SO16 packaging.	
1.4 Product Category	PMOS SUPERMESH products.	
1.5 Issue date	2018-03-09	

## 2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Domenico ARRIGO
2.1.2 Marketing Manager	Fulvio PULICELLI
2.1.3 Quality Manager	Alessandro PLATINI

## 3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication	ST Catania (Italy) / ST Ang Mo Kio (Singapore)

## 4. Description of change

	Old	New
4.1 Description	Wafer fab in ST Catania (Italy) for PMOS SUPERMESH. BOM on SO16 packaging: Glue type 8600-Standard Leadframe.	Wafer fab in ST Catania (Italy) and ST Ang Mo Kio (Singapore) for PMOS SUPERMESH Technology. Catania Wafer fab will stop the production of PMOS SUPERMESH from H2 2018. New BOM on SO16 packaging: Glue type 8200T- Rugged LeadFrame.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact	

## 5. Reason / motivation for change

5.1 Motivation	ST Ang Mo Kio will be validated as an additional wafer fab for PMOS SUPERMESH products in order to provide more flexibility in term of production and prepare the termination of the production of these products in ST Catania (Italy) New BOM occurs for process optimization and standardization.
5.2 Customer Benefit	MANUFACTURING FLEXIBILITY

## 6. Marking of parts / traceability of change

6.1 Description	New Finish Good codes.
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## 7. Timing / schedule

7.1 Date of qualification results	2018-01-21
7.2 Intended start of delivery	2018-04-16
7.3 Qualification sample available?	Upon Request

## 8. Qualification / Validation

8.1 Description	10676 RR007617CS6080.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2018-03-09
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9. Attachments (additional documentations)
10676 Public product.pdf 10676 RR007617CS6080.pdf 10676 RR007517CS6080.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	VIPER35HD	
	VIPER35HE	
	VIPER35LD	
	VIPER35LE	
	VIPER37HD	
	VIPER37HE	
	VIPER37LD	
	VIPER37LDTR	
	VIPER37LE	
	VIPER38HD	
	VIPER38HE	
	VIPER38LD	
	VIPER38LE	

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